ON Semiconductor

Is Now

# onsemi 

To learn more about onsemi ${ }^{T M}$, please visit our website at www.onsemi.com

[^0]
## NCV7381B0V2GEVB NCV7381BGEVK

# NCV7381B FlexRay ${ }^{\circledR}$ Transceiver Evaluation Board User's Manual 

## INTRODUCTION

The NCV7381B0V2GEVB evaluation board and NCV7381BGEVK evaluation kit provides flexible and convenient platform to evaluate, characterize and verify the operation of the NCV7381BDP0R2G FlexRay transceivers.

## DESCRIPTION

The NCV7381B is a single-channel FlexRay transceiver compliant with the FlexRay Electrical Physical Layer Specification Rev. 3.0.1, capable of communicating at speeds of up to $10 \mathrm{Mbit} / \mathrm{s}$. It provides differential transmit and receive capability between a wired FlexRay communication medium on one side and a protocol controller and a host on the other side.

NCV7381B mode control functionality is optimized for nodes permanently connected to car battery.

Additional details can be found in the NCV7381B datasheet.
The NCV7381B0V2GEVB Evaluation board is a reference design for stand-alone 2-channel FlexRay node. The board is intended to give designers easy, quick and convenient means for evaluation of NCV7381B FlexRay transceiver. The design incorporates complete node solution with possibility of modifications and small board size.

A set of two boards allows users to quickly start with the transceiver evaluation. The MCU is preprogrammed with simple mode control and FlexRay communication. The MCU firmware can be freely modified and reprogrammed if needed.

## BOARD HARDWARE

The evaluation board consists of an MCU with integrated 2-channel FlexRay communication controller interconnected with two separate FlexRay transceivers (NCV7381B), two switchable voltage regulators and peripherals. The board is ready for various modifications of power supply concept and FlexRay bus termination, and allows for simple extension of the system by unused MCU pins. The USB interface provides connectivity with standard PC. The address of each board can be easily modified by address switch what allows for building complex FlexRay network without need of reprogramming the MCU. Implemented High Speed CAN interface can be used as a diagnostic interface in a network built from several nodes. For evaluation purposes the NCV7381B evaluation board is populated with several LEDs and most of the transceiver signals are easily accessible to oscilloscope probes.

ON Semiconductor ${ }^{\circledR}$
www.onsemi.com
EVAL BOARD USER'S MANUAL


NCV7381B Pin Connections


Figure 1. NCV7381B0V2GEVB Evaluation Board

## GENERAL FEATURES

## FlexRay Transceiver

- Two separate FlexRay channels with NCV7381B transceiver compliant with the FlexRay Electrical Physical Layer Specification Rev. 3.0.1
- Reconfigurable bus termination - End node/Middle node
- Common mode Choke and additional ESD protection footprint
- SUBD-9 connectors - FlexRay bus
- Local Wake-up switch


## MCU

- 16-bit MC9S12XF family MCU with integrated FlexRay Communication Controller (Protocol Specification Rev. 2.1)
- Integrated CAN 2.0 A, B Controller
- Background Debug Module - single-wire communication with host development system
- 512 kB Flash
- 32 kB RAM
- 50 MHz maximum CPU bus frequency
- Relatively small 112-pin LQFP package


## Peripherals

- Optical isolated USB interface (USB to UART converter)
- Additional CAN interface
- All NCV7381B digital I/O pins connected to test points - easy connection to Logic Analyzer
- 8 general purpose LEDs
- Address switch


## Other

- Two Automotive Voltage regulators with Inhibit function (Input battery voltage up to 42 V )
- Power supplies voltage monitoring
- Instant 2-nodes FlexRay network with running communication by connecting two EVBs
- PC configuration software under development (available upon request)


## PCB Layout

- The FlexRay transceiver, the ESD protection and the common mode choke are placed near to the FlexRay the ECU connector
- The FlexRay signal lines (BP, BM) are decoupled from disturbances on the ECU board
- The routing of the FlexRay lines (BP, BM, TxD and TxEN) is symmetric.
- The distance between the lines BP and BM resp. TxD and TxEN is minimized.


## GETTING STARTED

The NCV7381BEVB board is fully assembled, pre-programmed and can be immediately used for evaluation. Only a few steps need be proceeded to get fully working simple FlexRay network.

Connect the evaluation boards as follows:

1. Set the boards to default configuration according to Jumpers and Default Configuration section.
2. Set a different board address on each board. One of the boards must be set with address 1 and is
then considered to be a Master Board. The node address is configurable by address switch (SW12) - see Address Switch section for more details.
3. Connect the boards according to Figure 2.
4. Optionally connect an oscilloscope to any test-point as needed.
5. Once the power supply is applied, FlexRay communication is initialized automatically.


Figure 2. Getting started setup connection

## NCV7381B0V2GEVB

## Operating Modes

The nodes can operate in two different operating modes:

- Normal mode - all the nodes continuously communicate over the FlexRay bus
- Sleep mode - the communication is suspended. Both NCV7381B FlexRay transceivers are switched to low-power Sleep operating mode. The VCC and VIO power supplies are switched off by NCV7381B INH output and the transceivers are powered from VBAT supply input. MCU is not running and the board can be only woken-up with one of the Local Wake-up pushbutton switches (SW70, SW80). Indication LEDs are switched off.


## Enter Sleep Mode Sequence

A transition to Sleep mode can be initiated by the node with address 1:

- Press and hold the Node1's \#IRQ pushbutton switch for more than 5 seconds. The GO_TO_SLEEP signal is transmitted over the FlexRay bus. All the nodes then synchronously stop the communication and switch to Sleep mode.


## Wake-up Sequence

The network operating in Sleep mode can be woken-up
by any node:

- NCV7381B Local Wake-up function - Press the Local Wake-up pushbutton switch on any node connected to the network. The corresponding FlexRay transceiver is woken-up from Sleep mode and activates its INH output. Consequently the VCC and VIO supply voltage regulators are activated and the MCU resumes operation in Normal mode.
- NCV7381B Remote Wake-up function - Once the first node is active, it automatically wakes up the rest of the network by sending FlexRay Remote Wakeup Pattern over the bus. As soon as all the nodes are woken-up and initialized, the FlexRay communication is restarted.


## LED Indication modes

Three LED indication modes are available - FlexRay communication indication, Status indication

Channel A and B. Press and hold the pushbutton for approximately 2 seconds to cycle between the indication modes.

- FlexRay communication indication - each LED is assigned to one slot according to LED number. The LED is blinking if the respective slot in FlexRay communication is active.


Figure 3. FlexRay communication indication

- FlexRay transceiver status indication - Channel A
- FlexRay transceiver status indication - Channel B
- LED1 - Local Wake-Up status
- LED2 - Remote Wake-up status
- LED3 - TxEN Timeout status
- LED4 - Bus Error status
- LED5 - VIO Undervoltage status
- LED6 - VCC Undervoltage status
- LED7 - VBAT Undervoltage status
- LED8 - Power-on status


Figure 4. FlexRay transceiver status indication
In FlexRay transceiver status indication mode, press the pushbutton shortly to read-out the status register.


Figure 5. Basic interface

## Power Supply Input Connector

Power supply input socket. Plug diameter 2.1 mm , length 14 mm . Maximum input voltage 42 V (Limited by onboard voltage regulators).


Figure 6. Power Supply Input Connector

## Aux Digital I/O Connector

This pin header contains 6 auxiliary MCU signals - one SPI interface (4 pins) and one UART interface (2 pins). These signals can be also used as general input/output signals for debugging or other purposes.


Figure 7. Aux Digital I/O Connector

## CAN Backbone Connectors

CAN backbone network is a parallel connection of multiple boards. Each board contains two equivalent connectors in parallel, and thus whole network can be built using simple point-to-point twisted pair cables.


Figure 8. CAN Backbone Connectors

## USB Interface

Standard B type USB socket is used for connection to PC. USB interface is bus powered and electrically isolated from the rest of the board, so it is not possible to supply this board via USB.

## FlexRay CC Strobe Output Signals

The MCU FlexRay block provides a number of strobe signals for observing internal protocol timing related signals in the protocol engine.


Figure 9. FlexRay CC Strobe Output Signals
These signals are connected to STRB pin header:

## BDM Connector (MCU Debugging Interface)

The BDM module provides a single-wire communication with host development system (Programming and debugging interface).


Figure 10. BDM Connector (MCU Debugging Interface)

## FlexRay BD Digital Signals Test Points Headers

These headers are intended to be used as a test points for digital probes. Headers contain all FlexRay BD digital input and output signals.

Test points for both FlexRay channel A and channel B are placed on separated headers (J73 - channel A, J83 channel B).


Figure 11. FlexRay BD Digital Signals Test Points Headers

## FlexRay BD Analog Signals Test Points

Each FlexRay channel contains 4 analog test points:

- INH1 - Bus Driver Inhibit 1 output
- INH2 - Bus Driver Inhibit 2 output
- BP - FlexRay Bus Plus terminal
- BM - FlexRay Bus Minus terminal


## FlexRay Bus Connectors

FlexRay EPL Specification [2] does not prescribe certain connectors for FlexRay systems. Commonly used 9-pin D-Sub connectors meet the defined constraints such as maximum contact resistance and connector impedance.

Table 1. FLEXRAY CONNECTOR

| Pin \# | Signal | Description | Connection | ESD Protection |
| :---: | :---: | :---: | :---: | :---: |
| 1 | - | Reserved | Not Connected |  |
| 2 | FR_BM | BM Bus Line | BM | Yes (Optional) |
| 3 | FR_GND | Ground | GND |  |
| 4 | - | Reserved | Not Connected |  |
| 5 | - | Reserved | Not Connected |  |
| 6 | - | Reserved | Not Connected |  |
| 7 | FR_BP | BP Bus Line | BP | Yes (Optional) |
| 8 | - | Reserved | Not Connected |  |
| 9 | (FR_VBAT) | Optional FR External Supply | Main Supply Line | Yes |

Connector type: 9-pin D-Sub (DIN41652 or corresponding
international standard), plug (male).

JUMPERS AND DEFAULT CONFIGURATION


Figure 12. Jumpers and Soldering Straps

Table 2. 2-PIN JUMPER


Table 3. 2-PIN JUMPER

| 123 |  |
| :---: | :---: |
| $\square \square$ | Open |
| $\square \square$ | Closed position 1-2 |
| $\square$ | Closed position 2-3 |

Table 4. JUMPERS CONFIGURATION

| Jumper | Function | Configuration | Description | Default |
| :---: | :---: | :---: | :---: | :---: |
| J20 | MCU VCC 5 V State | Open | Controlled by bd_INH1_x | Open |
|  |  | Closed | Always On |  |
| J23 | BD VIO power supply selection | Open | BD VIO Disconnected | Closed 1-2 |
|  |  | Closed 1-2 | BD VIO Connected to MCU VCC |  |
|  |  | Closed 2-3 | BD VIO - External VIO power supply |  |
| J30 | BD VCC State | Open | Controlled by MCU | Closed |
|  |  | Closed | Controlled by bd_INHx_x |  |
| J32 | BD VCC Inhibit source (Ch A) | Open | bd_INH2_A | Closed |
|  |  | Closed | bd_INH1_A |  |
| J33 | BD VCC Inhibit source (Ch B) | Open | bd_INH2_B | Closed |
|  |  | Closed | bd_INH1_B |  |
| J40 | CAN bus terminator | Open | Without Termination | Closed |
|  |  | Closed | With $120 \Omega$ Termination |  |

Table 4. JUMPERS CONFIGURATION (continued)

| Jumper | Function | Configuration | Description | Default |
| :---: | :--- | :---: | :--- | :---: |
| J52 | General purpose LED | Open | LEDs Disabled | Closed |
|  |  | Closed | LEDs Enabled |  |
|  | Bus Driver VBAT supply (Ch A) | Open | BD VBAT Disconnected | Closed |
|  |  | Closed | BD VBAT Connected |  |
| J71 | Bus Driver VBUF supply (Ch A) | Open | BD VBUF Disconnected |  |
|  |  | Closed | BD VBUF Connected to BD VCC |  |
| J80 | Bus Driver VBAT supply (Ch B) | Open | BD VBAT Disconnected |  |
|  |  | Closed | BD VBAT Connected | Open |

## SWITCHES AND PUSHBUTTONS



- SW10 - MCU Reset pushbutton switch
- SW11 - MCU External interrupt pushbutton switch
- SW12 - 8-way DIP switch. The function depends on the MCU program. By default it is used for setting a node address.
- SW70 - FlexRay Transceiver Local Wake-up pushbutton switch (Channel A)
- SW80 - FlexRay Transceiver Local Wake-up pushbutton switch (Channel B)

Figure 13. Switches Description

## Address Switch

This switch is used for setting a node address. Each board is programmed with the same firmware, therefore to distinguish individual nodes from each other and map the data to individual communication slots, every node in the network must be assigned a unique number.

LSB is situated on the left!
ON means the particular switch is closed and output is

## Logical 0!

OFF means the particular switch is open and output is Logical 1!

01234567


Figure 14. Address Configuration Switch
The switch configuration shown in this figure means binary 0 b 00000010 (Node address is set to 2 ).

## MCU Reset Pushbutton Switch

This switch is used to generate an external reset event at the MCU reset pin.

## MCU External Interrupt Pushbutton Switch

The MCU interrupt module supports one maskable interrupt input. This input is connected to SW11.

## Local Wake-up Pushbutton Switch

The NCV7381B FlexRay transceiver supports Local Wake-up event detection. If a falling edge is recognized on WAKE pin, a local wake-up is detected. These switches (one for each FlexRay channel) can be used to generate a Local wake-up event that is normally generated by e.g. mechanical switch.

## LEDs

Three power supply LEDs indicate proper function of the voltage regulators. In case the MCU and the NCV7381B transceivers I/O cells use the same power supply (as by default), the MCU VCC LED and BD VIO LED signalling is also the same.

The board contains a bank of eight general purpose LEDs (Green). Their function depends on the MCU program. There is also a USB indication LED which is used to indicate any ongoing USB data transmission.


Figure 15. LEDs Description


Figure 16. NCV7381B EVB Block Diagram

TYPICAL APPLICATION DIAGRAM


Figure 17. Typical Application Diagram

Table 5. RECOMMENDED EXTERNAL COMPONENTS FOR THE APPLICATION DIAGRAM

| Component | Function | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{C}_{\text {VBAT }}$ | Decoupling capacitor on battery line, ceramic |  | 100 |  | nF |
| CVcc | Decoupling capacitor on $\mathrm{V}_{\text {CC }}$ supply line, ceramic |  | 100 |  | nF |
| $\mathrm{C}_{\mathrm{VIO}}$ | Decoupling capacitor on $\mathrm{V}_{10}$ supply line, ceramic |  | 100 |  | nF |
| RWAKE1 | Pull-up resistor on WAKE pin |  | 33 |  | k $\Omega$ |
| RWAKE2 | Serial protection resistor on WAKE pin |  | 3.3 |  | $k \Omega$ |
| R BUS1 | Bus termination resistor (Note 1) |  | 47.5 |  | $\Omega$ |
| R BUS2 | Bus termination resistor (Note 1) |  | 47.5 |  | $\Omega$ |
| $\mathrm{C}_{\text {BUS }}$ | Common-mode stabilizing capacitor, ceramic (Note 2) |  | 4.7 |  | nF |
| CMC | Common-mode choke |  | 100 |  | $\mu \mathrm{H}$ |

1. Tolerance $\pm 1 \%$, type 0805
2. Tolerance $\pm 20 \%$, type 0805

## POWER SUPPLY

The evaluation board can be powered either via DC power supply input socket with plug diameter 2.1 mm and length 14 mm or by one of the FlexRay bus connectors (See the

FlexRay Bus ConnectorsFlexRay bus connector (Channel A) section). Maximum input voltage ( 42 V ) is limited by on-board voltage regulators input voltage range.

## SPLIT TERMINATION

In order to achieve better EMC performance, it is recommended to make use of so-called split termination in
all ECUs, where the termination resistance $\mathrm{R}_{\mathrm{T}}$ is split into two equal parts RTA and Rtв [2].


NOTE: The serial RC combination (R1, C1) at the center tap of the split termination provides a termination to GND for common mode signals. R1 is preferably omitted. Typical values are given in the following table.

Figure 18. ECU with split termination [2]

Table 6. TERMINATION PARAMETERS

| Name | Description | Typ. | Unit |
| :---: | :--- | :---: | :---: |
| R 1 | Resistor | $<10$ | $\Omega$ |
| C 1 | Capacitor | 4700 |  |
| $2 \times\left\|\mathrm{R}_{\mathrm{TA}}-\mathrm{R}_{\mathrm{TB}}\right\| /\left(\mathrm{R}_{\mathrm{TA}}+\mathrm{R}_{\mathrm{TB}}\right)$ | Matching of termination resistors | $\leq 2$ | pF |

[^1]
## Standard termination

Recommended bus split termination is shown in the Figure 19. Considering passive network, without active stars, proper termination should be applied at the two nodes
that have the maximum electrical distance on the bus. The sum of termination resistors values should match the nominal cable impedance. At other nodes a high-ohmic split termination should be applied.


Figure 19. Basic Split Termination and Common Mode Choke Connection

Table 7. BASIC SPLIT TERMINATION PARAMETERS

| Name | Value |  |  |  |
| :---: | :--- | :---: | :---: | :---: |
|  |  | Description |  | End node | Middle node |
| Unit |  |  |  |
|  | Termination resistors | 47 | 1300 | $\Omega$ |
| C 1 | Capacitor | 4700 | 4700 | pF |

## Custom Termination

In some cases a specific termination topology is required for middle modes. Such termination connection and typical values are shown in Figure 21 and Table 8.


Figure 20. End Node Split Termination


Figure 21. Middle Node Split Termination

Table 8. CUSTOM SPLIT TERMINATION PARAMETERS

| Name | Value |  |  |  |
| :---: | :--- | :---: | :---: | :---: |
|  |  |  | Middle node | Unit |
|  | Termination resistors | 47 | 24 |  |
| C 1 | Capacitor | 4700 | 4.7 | pF |
| R 1 | Resistor | - | 47 | $\Omega$ |
| $\mathrm{C}_{\mathrm{TA}}, \mathrm{C}_{\mathrm{TB}}$ | Termination capacitors | - | 100 | pF |

## COMMON MODE CHOKE

A common mode choke (CMC) is used to improve the emission and immunity performance. The function of the common mode choke is to force the current in both signal wires to be of the same strength, but opposite direction. Therefore, the choke represents high impedance for
common mode signals. The parasitic stray inductance should be as low as possible in order to keep oscillations on the bus low. The common mode choke is placed between transceiver and split termination [2]. CMC requirements are listed in Table 9. Basic connection is shown in Figure 19.

Table 9. COMMON MODE CHOKE REQUIEREMENTS [2]

| Name | Description | Typ. | Unit |
| :---: | :--- | :---: | :---: |
| $\mathrm{R}_{\mathrm{CMC}}$ | Resistance per line | $\leq 1$ | $\Omega$ |
| $\mathrm{~L}_{\mathrm{CMC}}$ | Main inductance | $\geq 100$ | $\mu \mathrm{H}$ |
| $\mathrm{L}_{\sigma}$ | Stray inductance | $<1$ | $\mu \mathrm{H}$ |

## MCU PROGRAMMING INTERFACE

The NCV7381B0V2GEVB firmware can be freely reprogrammed using MCU programming and debugging interface (J10). The microcontroller can be programmed


Figure 22. PEmicro USB Multilink BDM module (Discontinued)
with PEmicro's USB Multilink BDM (Discontinued) or Universal module.


Figure 23. PEmicro USB Multilink Universal Debug module

## SOFTWARE DEVELOPMENT TOOL

Freescale CodeWarrior ${ }^{\circledR}$ Development Studio for HCS12(X) Microcontrollers (Classic IDE) v5.2 (http://www.nxp.com/) can be used for programming and
debugging of the microcontroller firmware. The PEmicro USB Multilink interface is directly supported.


NOTE: The NCV7381B EVB firmware can be downloaded from ON Semiconductor web site (http://www.onsemi.com/).
Figure 24. CodeWarrior Development Studio
SCHEMATIC



Figure 26. PCB Top Assembly Drawing


Figure 27. PCB Bottom Assembly Drawing

## NCV7381B0V2GEVB



Figure 28. PCB Top Composite Drawing


Figure 29. PCB Bottom Composite Drawing (Mirrored)

## PCB GENERAL PARAMETERS

- Material:
- CU Plating Thickness:
- Surface Treatment:
- Solder Resist:


## REFERENCES

[1] ON Semiconductor. NCV7381B/D, Product Datasheet, Rev. 4, April 2018, www.onsemi.com
[2] FlexRay Consortium. FlexRay Communications System - Electrical Physical Layer Specification, V3.0.1., October 2010

## DIMENSIONS

- Length: $\quad 107.2 \mathrm{~mm}(4220 \mathrm{mil})$
- Width:
- Thickness: $70.4 \mathrm{~mm}(2770 \mathrm{mil})$ $1.5 \mathrm{~mm}(60 \mathrm{mil})$
- Minimum Clearance: $0.25 \mathrm{~mm}(9.842 \mathrm{mil})$
[3] FlexRay Consortium. FlexRay Communications System - Physical Layer EMC Measurement Specification, V3.0.1., October 2010

FlexRay is a registered trademark of Daimler Chrysler AG.
CodeWarrior is a registered trademark of NXP B.V.
ON Semiconductor and (iN) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

## LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com
N. American Technical Support: 800-282-9855 Toll Free

USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421337902910

ON Semiconductor Website: www.onsemi.com Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative


[^0]:    
    
    
    
    
    
    
    
    
    
    
    
     Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner. Other names and brands may be claimed as the property of others.

[^1]:    NOTES: For $\mathrm{R}_{\text {TA }}$ and $\mathrm{R}_{\text {TB }}$ the use of $1 \%$ tolerated resistors leads to a matching of $2 \%$.
    The better the matching of the split termination resistors $\mathrm{R}_{\mathrm{TA}}$ and $\mathrm{R}_{\mathrm{TB}}$, the lower the electromagnetic emission.

